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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	76
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-1
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/c161pilfcafxuma1

Pin Configuration MQFP Package

(top view)

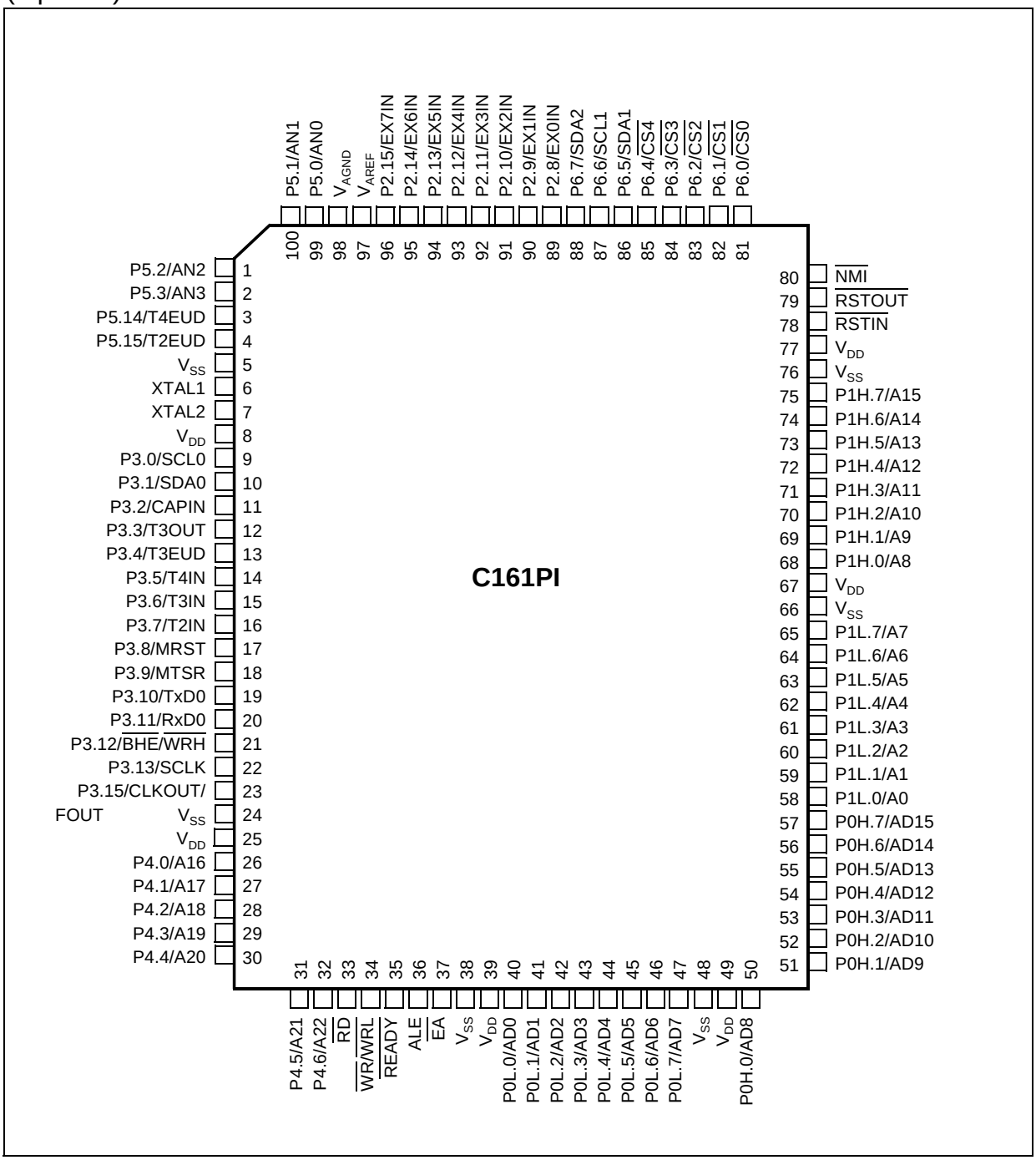


Figure 2

Central Processing Unit (CPU)

The main core of the CPU consists of a 4-stage instruction pipeline, a 16-bit arithmetic and logic unit (ALU) and dedicated SFRs. Additional hardware has been spent for a separate multiply and divide unit, a bit-mask generator and a barrel shifter.

Based on these hardware provisions, most of the C161PI's instructions can be executed in just one machine cycle which requires 2 CPU clocks (4 TCL). For example, shift and rotate instructions are always processed during one machine cycle independent of the number of bits to be shifted. All multiple-cycle instructions have been optimized so that they can be executed very fast as well: branches in 2 cycles, a 16 × 16 bit multiplication in 5 cycles and a 32-/16 bit division in 10 cycles. Another pipeline optimization, the so-called 'Jump Cache', reduces the execution time of repeatedly performed jumps in a loop from 2 cycles to 1 cycle.

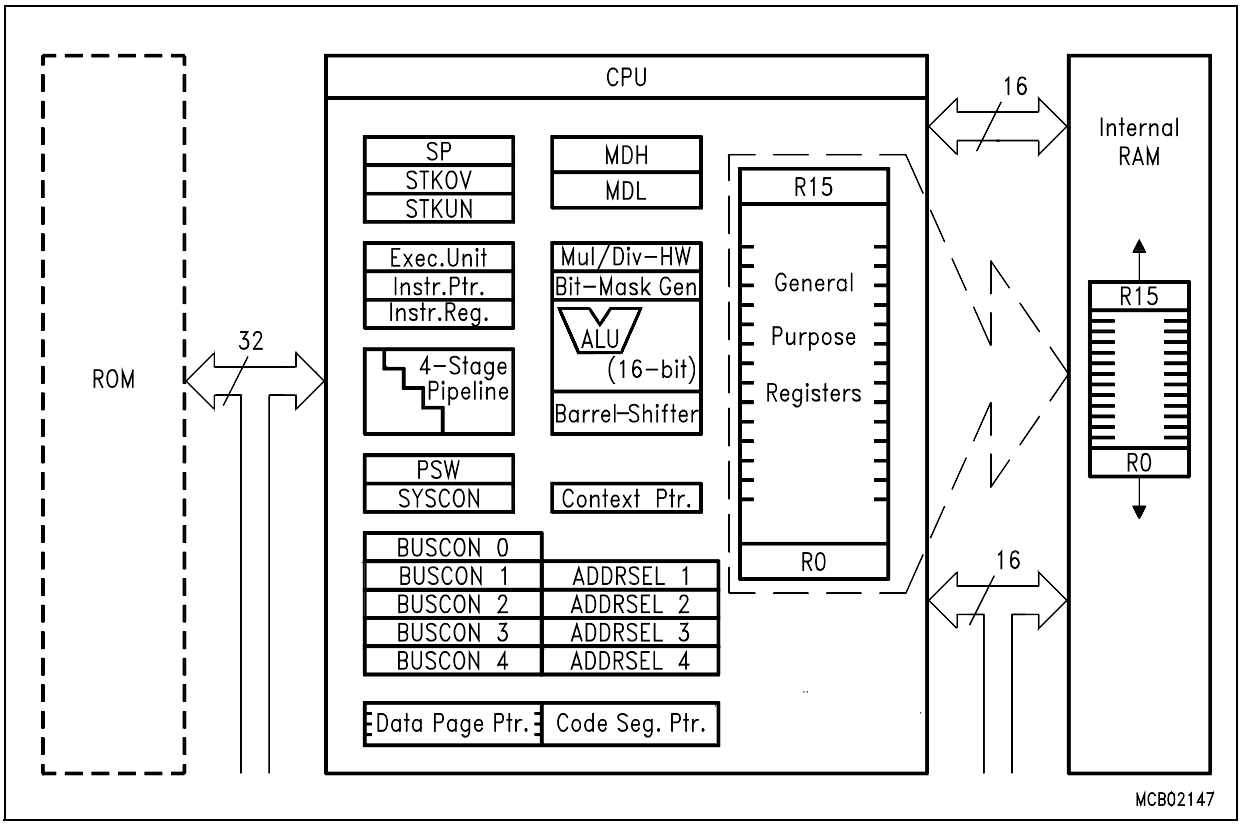


Figure 5 CPU Block Diagram

The C161PI also provides an excellent mechanism to identify and to process exceptions or error conditions that arise during run-time, so-called ‘Hardware Traps’. Hardware traps cause immediate non-maskable system reaction which is similar to a standard interrupt service (branching to a dedicated vector table location). The occurence of a hardware trap is additionally signified by an individual bit in the trap flag register (TFR). Except when another higher prioritized trap service is in progress, a hardware trap will interrupt any actual program execution. In turn, hardware trap services can normally not be interrupted by standard or PEC interrupts.

The following table shows all of the possible exceptions or error conditions that can arise during run-time:

Table 3 Hardware Trap Summary

Exception Condition	Trap Flag	Trap Vector	Vector Location	Trap Number	Trap Prio
Reset Functions:					
Hardware Reset		RESET	$00'0000_H$	00_H	III
Software Reset		RESET	$00'0000_H$	00_H	III
Watchdog Timer Overflow		RESET	$00'0000_H$	00_H	III
Class A Hardware Traps:					
Non-Maskable Interrupt	NMI	NMITRAP	$00'0008_H$	02_H	II
Stack Overflow	STKOF	STOTRAP	$00'0010_H$	04_H	II
Stack Underflow	STKUF	STUTRAP	$00'0018_H$	06_H	II
Class B Hardware Traps:					
Undefined Opcode	UNDOPC	BTRAP	$00'0028_H$	$0A_H$	I
Protected Instruction Fault	PRTFLT	BTRAP	$00'0028_H$	$0A_H$	I
Illegal Word Operand Access	ILLOPA	BTRAP	$00'0028_H$	$0A_H$	I
Illegal Instruction Access	ILLINA	BTRAP	$00'0028_H$	$0A_H$	I
Illegal External Bus Access	ILLBUS	BTRAP	$00'0028_H$	$0A_H$	I
Reserved			$[2C_H – 3C_H]$	$[0B_H – 0F_H]$	
Software Traps: TRAP Instruction			Any $[00'0000_H – 00'01FC_H]$ in steps of 4_H	Any $[00_H – 7F_H]$	Current CPU Priority

Parallel Ports

The C161PI provides up to 76 IO lines which are organized into six input/output ports and one input port. All port lines are bit-addressable, and all input/output lines are individually (bit-wise) programmable as inputs or outputs via direction registers. The I/O ports are true bidirectional ports which are switched to high impedance state when configured as inputs. The output drivers of three IO ports can be configured (pin by pin) for push/pull operation or open-drain operation via control registers. The other IO ports operate in push/pull mode, except for the I²C interface pins which are open drain pins only. During the internal reset, all port pins are configured as inputs.

All port lines have programmable alternate input or output functions associated with them. All port lines that are not used for these alternate functions may be used as general purpose IO lines.

PORT0 and PORT1 may be used as address and data lines when accessing external memory, while Port 4 outputs the additional segment address bits A22/19/17...A16 in systems where segmentation is enabled to access more than 64 KBytes of memory.

Port 3 includes alternate functions of timers, serial interfaces, the optional bus control signal $\overline{\text{BHE}}$ and the system clock output CLKOUT (or the programmable frequency output FOUT).
Port 5 is used for the analog input channels to the A/D converter or timer control signals.

Port 6 provides the optional chip select signals and interface lines for the I²C module.

The edge characteristics (transition time) of the C161PI's port drivers can be selected via the Port Driver Control Register (PDCR).

Table 4 Instruction Set Summary (continued)

Mnemonic	Description	Bytes
MOV(B)	Move word (byte) data	2 / 4
MOVBS	Move byte operand to word operand with sign extension	2 / 4
MOVBZ	Move byte operand to word operand. with zero extension	2 / 4
JMPA, JMPI, JMPR	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
J(N)B	Jump relative if direct bit is (not) set	4
JBC	Jump relative and clear bit if direct bit is set	4
JNBS	Jump relative and set bit if direct bit is not set	4
CALLA, CALLI, CALLR	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH, POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack und update register with word operand	4
RET	Return from intra-segment subroutine	2
RETS	Return from inter-segment subroutine	2
RETP	Return from intra-segment subroutine and pop direct word register from system stack	2
RETI	Return from interrupt service subroutine	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Enter Power Down Mode (supposes $\overline{\text{NMI}}$-pin being low)	4
SRVWDT	Service Watchdog Timer	4
DISWDT	Disable Watchdog Timer	4
EINIT	Signify End-of-Initialization on RSTOUT-pin	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTended Register sequence	2
EXTP(R)	Begin EXTended Page (and Register) sequence	2 / 4
EXTS(R)	Begin EXTended Segment (and Register) sequence	2 / 4
NOP	Null operation	2

Table 5 C161PI Registers, Ordered by Name (continued)

Name		Physical Address		8-Bit Addr.	Description	Reset Value
CC12IC	**b**	$FF90_H$		$C8_H$	External Interrupt 4 Control Register	0000_H
CC13IC	**b**	$FF92_H$		$C9_H$	External Interrupt 5 Control Register	0000_H
CC14IC	**b**	$FF94_H$		CA_H	External Interrupt 6 Control Register	0000_H
CC15IC	**b**	$FF96_H$		CB_H	External Interrupt 7 Control Register	0000_H
CP		$FE10_H$		08_H	CPU Context Pointer Register	$FC00_H$
CRIC	**b**	$FF6A_H$		$B5_H$	GPT2 CAPREL Interrupt Ctrl. Register	0000_H
CSP		$FE08_H$		04_H	CPU Code Segment Pointer Register (8 bits, not directly writeable)	0000_H
DP0L	**b**	$F100_H$	**E**	80_H	P0L Direction Control Register	00_H
DP0H	**b**	$F102_H$	**E**	81_H	P0H Direction Control Register	00_H
DP1L	**b**	$F104_H$	**E**	82_H	P1L Direction Control Register	00_H
DP1H	**b**	$F106_H$	**E**	83_H	P1H Direction Control Register	00_H
DP2	**b**	$FFC2_H$		$E1_H$	Port 2 Direction Control Register	0000_H
DP3	**b**	$FFC6_H$		$E3_H$	Port 3 Direction Control Register	0000_H
DP4	**b**	$FFCA_H$		$E5_H$	Port 4 Direction Control Register	00_H
DP6	**b**	$FFCE_H$		$E7_H$	Port 6 Direction Control Register	00_H
DPP0		$FE00_H$		00_H	CPU Data Page Pointer 0 Register (10 bits)	0000_H
DPP1		$FE02_H$		01_H	CPU Data Page Pointer 1 Reg. (10 bits)	0001_H
DPP2		$FE04_H$		02_H	CPU Data Page Pointer 2 Reg. (10 bits)	0002_H
DPP3		$FE06_H$		03_H	CPU Data Page Pointer 3 Reg. (10 bits)	0003_H
EXICON	**b**	$F1C0_H$	**E**	$E0_H$	External Interrupt Control Register	0000_H
ICADR		$ED06_H$	**X**	---	I²C Address Register	$0XXX_H$
ICCFG		$ED00_H$	**X**	---	I²C Configuration Register	$XX00_H$
ICCON		$ED02_H$	**X**	---	I²C Control Register	0000_H
ICRTB		$ED08_H$	**X**	---	I²C Receive/Transmit Buffer	XX_H
ICST		$ED04_H$	**X**	---	I²C Status Register	0000_H
IDCHIP		$F07C_H$	**E**	$3E_H$	Identifier	$09XX_H$
IDMANUF		$F07E_H$	**E**	$3F_H$	Identifier	1820_H
IDMEM		$F07A_H$	**E**	$3D_H$	Identifier	0000_H

DC Characteristics (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Output low voltage (all other outputs)	V_{OL1} CC	–	0.45	V	I_{OL} = 1.6 mA
Output high voltage [1] (PORT0, PORT1, Port 4, ALE, $\overline{RD}$, $\overline{WR}$, $\overline{BHE}$, CLKOUT, $\overline{RSTOUT}$)	V_{OH} CC	2.4	–	V	I_{OH} = -2.4 mA
		0.9 V_{DD}	–	V	I_{OH} = -0.5 mA
Output high voltage [1] (all other outputs)	V_{OH1} CC	2.4	–	V	I_{OH} = -1.6 mA
		0.9 V_{DD}	–	V	I_{OH} = -0.5 mA
Input leakage current (Port 5)	I_{OZ1} CC	–	±200	nA	0.45V < V_{IN} < V_{DD}
Input leakage current (all other)	I_{OZ2} CC	–	±500	nA	0.45V < V_{IN} < V_{DD}
$\overline{RSTIN}$ inactive current [2]	I_{RSTH} [3]	–	-10	µA	V_{IN} = V_{IH1}
$\overline{RSTIN}$ active current [2]	I_{RSTL} [4]	-100	–	µA	V_{IN} = V_{IL}
Read/Write inactive current [5]	I_{RWH} [3]	–	-40	µA	V_{OUT} = 2.4 V
Read/Write active current [5]	I_{RWL} [4]	-500	–	µA	V_{OUT} = V_{OLmax}
ALE inactive current [5]	I_{ALEL} [3]	–	40	µA	V_{OUT} = V_{OLmax}
ALE active current [5]	I_{ALEH} [4]	500	–	µA	V_{OUT} = 2.4 V
Port 6 inactive current [5]	I_{P6H} [3]	–	-40	µA	V_{OUT} = 2.4 V
Port 6 active current [5]	I_{P6L} [4]	-500	–	µA	V_{OUT} = V_{OL1max}
PORT0 configuration current [5]	I_{P0H} [3]	–	-10	µA	V_{IN} = V_{IHmin}
	I_{P0L} [4]	-100	–	µA	V_{IN} = V_{ILmax}
XTAL1 input current	I_{IL} CC	–	±20	µA	0 V < V_{IN} < V_{DD}
Pin capacitance [6] (digital inputs/outputs)	C_{IO} CC	–	10	pF	f = 1 MHz T_A = 25 °C
Power supply current (5V active) with all peripherals active	I_{DD5}	–	1 + 2*f_{CPU}	mA	$\overline{RSTIN}$ = V_{IL2} f_{CPU} in [MHz] [7]
Idle mode supply current (5V) with all peripherals active	I_{IDX5}	–	1 + 0.8*f_{CPU}	mA	$\overline{RSTIN}$ = V_{IH1} f_{CPU} in [MHz] [7]
Idle mode supply current (5V) with all peripherals deactivated, PLL off, SDD factor = 32	I_{IDO5} [8]	–	500 + 50*f_{OSC}	µA	$\overline{RSTIN}$ = V_{IH1} f_{OSC} in [MHz] [7]

DC Characteristics (Reduced Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input low voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IL1} SR	– 0.5	0.3 V_{DD}	V	–
Input low voltage (TTL)	V_{IL} SR	– 0.5	0.8	V	–
Input low voltage (Special Threshold)	V_{ILS} SR	– 0.5	1.3	V	–
Input high voltage $\overline{\text{RSTIN}}$	V_{IH1} SR	0.6 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage XTAL1, P3.0, P3.1, P6.5, P6.6, P6.7	V_{IH2} SR	0.7 V_{DD}	V_{DD} + 0.5	V	–
Input high voltage (TTL)	V_{IH} SR	1.8	V_{DD} + 0.5	V	–
Input high voltage (Special Threshold)	V_{IHS} SR	0.8 V_{DD} - 0.2	V_{DD} + 0.5	V	–
Input Hysteresis (Special Threshold)	HYS	250	–	mV	–
Output low voltage (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$)	V_{OL} CC	–	0.45	V	I_{OL} = 1.6 mA
Output low voltage P3.0, P3.1, P6.5, P6.6, P6.7	V_{OL2} CC	–	0.4	V	I_{OL2} = 1.6 mA
Output low voltage (all other outputs)	V_{OL1} CC	–	0.45	V	I_{OL} = 1.0 mA
Output high voltage [1] (PORT0, PORT1, Port 4, ALE, $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{BHE}}$, CLKOUT, $\overline{\text{RSTOUT}}$)	V_{OH} CC	0.9 V_{DD}	–	V	I_{OH} = -0.5 mA
Output high voltage [1] (all other outputs)	V_{OH1} CC	0.9 V_{DD}	–	V	I_{OH} = -0.25 mA
Input leakage current (Port 5)	I_{OZ1} CC	–	±200	nA	0.45V < V_{IN} < V_{DD}
Input leakage current (all other)	I_{OZ2} CC	–	±500	nA	0.45V < V_{IN} < V_{DD}
$\overline{\text{RSTIN}}$ inactive current [2]	I_{RSTH} [3]	–	-10	µA	V_{IN} = V_{IH1}

AC Characteristics
Definition of Internal Timing

The internal operation of the C161PI is controlled by the internal CPU clock f_{CPU}. Both edges of the CPU clock can trigger internal (e.g. pipeline) or external (e.g. bus cycles) operations.

The specification of the external timing (AC Characteristics) therefore depends on the time between two consecutive edges of the CPU clock, called “TCL” (see figure below).

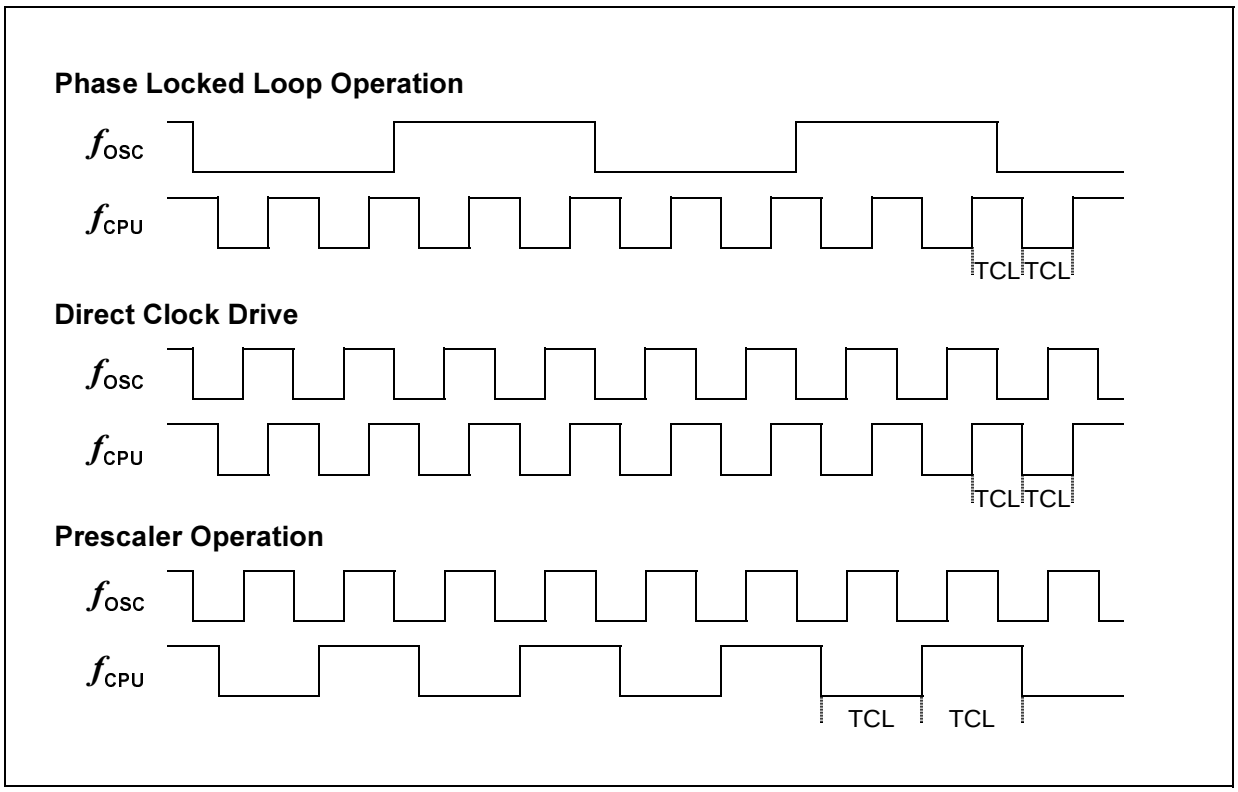


Figure 11 Generation Mechanisms for the CPU Clock

The CPU clock signal f_{CPU} can be generated from the oscillator clock signal f_{OSC} via different mechanisms. The duration of TCLs and their variation (and also the derived external timing) depends on the used mechanism to generate f_{CPU}. This influence must be regarded when calculating the timings for the C161PI.

Note: The example for PLL operation shown in the fig. above refers to a PLL factor of 4.

The used mechanism to generate the CPU clock is selected during reset via the logic levels on pins P0.15-13 (P0H.7-5).

The table below associates the combinations of these three bits with the respective clock generation mode.

The timings listed in the AC Characteristics that refer to TCLs therefore must be calculated using the minimum TCL that is possible under the respective circumstances.

The actual minimum value for TCL depends on the jitter of the PLL. As the PLL is constantly adjusting its output frequency so it corresponds to the applied input frequency (crystal or oscillator) the relative deviation for periods of more than one TCL is lower than for one single TCL (see formula and figure below).
For a period of ***N*** * TCL the minimum value is computed using the corresponding deviation D_N:

$(N * TCL)_{min} = N * TCL_{NOM} - D_N$ $\quad D_N\,[ns] = \pm(13.3 + N*6.3) / f_{CPU}\,[MHz]$,
where ***N*** = number of consecutive TCLs $\quad$ and $1 \le N \le 40$.

So for a period of 3 TCLs @ 25 MHz (i.e. ***N*** = 3): $D_3 = (13.3 + 3 * 6.3) / 25 = 1.288$ ns, and $(3TCL)_{min} = 3TCL_{NOM} - 1.288$ ns = 58.7 ns (@ f_{CPU} = 25 MHz).

This is especially important for bus cycles using waitstates and e.g. for the operation of timers, serial interfaces, etc. For all slower operations and longer periods (e.g. pulse train generation or measurement, lower baudrates, etc.) the deviation caused by the PLL jitter is neglectible.

Note: For all periods longer than 40 TCL the N=40 value can be used (see figure below).

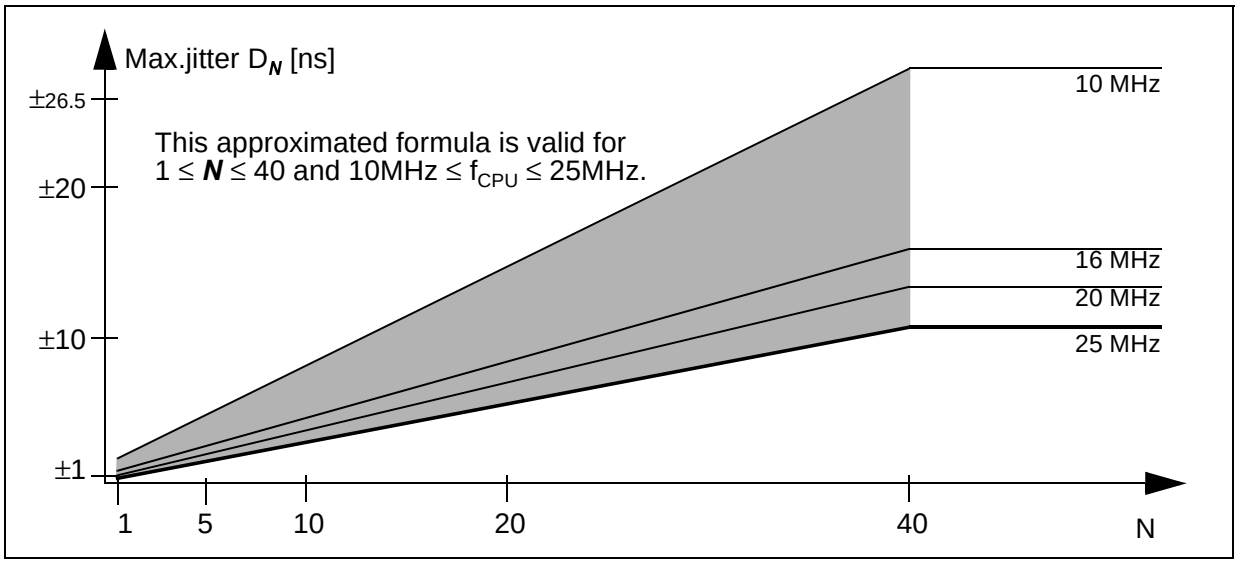


Figure 12 Approximated Maximum Accumulated PLL Jitter

Sample time and conversion time of the C161PI's A/D Converter are programmable. The table below should be used to calculate the above timings.
The limit values for f_{BC} must not be exceeded when selecting ADCTC.

Table 9 A/D Converter Computation Table

ADCON.15|14 (ADCTC)	A/D Converter Basic clock f_{BC}	ADCON.13|12 (ADSTC)	Sample time t_S
00	f_{CPU} / 4	00	t_{BC} * 8
01	f_{CPU} / 2	01	t_{BC} * 16
10	f_{CPU} / 16	10	t_{BC} * 32
11	f_{CPU} / 8	11	t_{BC} * 64

Converter Timing Example:

Assumptions:	f_{CPU}	= 25 MHz (i.e. t_{CPU} = 40 ns), ADCTC = '00', ADSTC = '00'.
Basic clock	f_{BC}	= f_{CPU} / 4 = 6.25 MHz, i.e. t_{BC} = 160 ns.
Sample time	t_S	= t_{BC} * 8 = 1280 ns.
Conversion time	t_C	= t_S + 40 t_{BC} + 2 t_{CPU} = (1280 + 6400 + 80) ns = 7.8 µs.

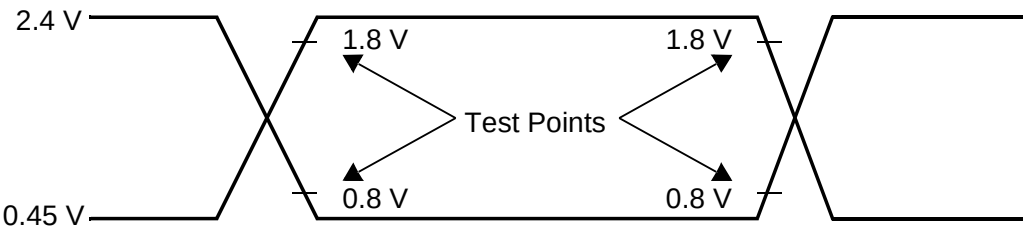
Memory Cycle Variables

The timing tables below use three variables which are derived from the BUSCONx registers and represent the special characteristics of the programmed memory cycle. The following table describes, how these variables are to be computed.

Table 10 Memory Cycle Variables

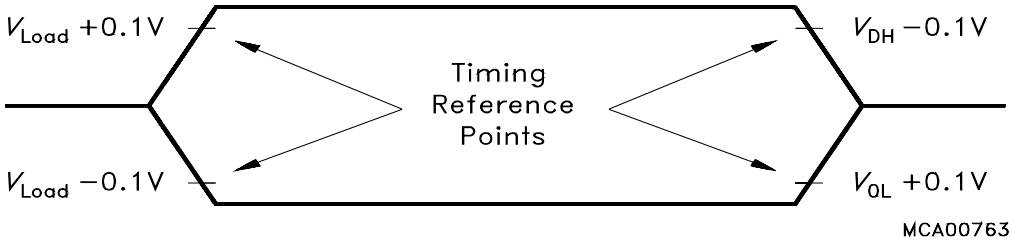
Description	Symbol	Values
ALE Extension	t_A	TCL * <ALECTL>
Memory Cycle Time Waitstates	t_C	2TCL * (15 - <MCTC>)
Memory Tristate Time	t_F	2TCL * (1 - <MTTC>)

Testing Waveforms



AC inputs during testing are driven at 2.4 V for a logic ‘1’ and 0.45 V for a logic ‘0’.
Timing measurements are made at V_{IH} min for a logic ’1’ and V_{IL} max for a logic ’0’.

Figure 14 Input Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs, but begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs (I_{OH}/I_{OL} = 20 mA).

Figure 15 Float Waveforms

Multiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 6 TCL + 2t_A + t_C + t_F (120 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
Data valid to $\overline{\text{WrCS}}$	t_{50}	CC	26 + t_C	–	2TCL - 14 + t_C	–	ns
Data hold after $\overline{\text{RdCS}}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{\text{RdCS}}$	t_{52}	SR	–	20 + t_F	–	2TCL - 20 + t_F	ns
Address hold after $\overline{\text{RdCS}}$, $\overline{\text{WrCS}}$	t_{54}	CC	20 + t_F	–	2TCL - 20 + t_F	–	ns
Data hold after $\overline{\text{WrCS}}$	t_{56}	CC	20 + t_F	–	2TCL - 20 + t_F	–	ns

1) These parameters refer to the latched chip select signals ($\overline{\text{CSxL}}$). The early chip select signals ($\overline{\text{CSxE}}$) are specified together with the address and signal $\overline{\text{BHE}}$ (see figures below).

Multiplexed Bus (Reduced Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 6 TCL + $2t_A$ + t_C + t_F (150 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
			min.	max.	min.	max.	
Data hold after $\overline{\text{RdCS}}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{\text{RdCS}}$	t_{52}	SR	–	30 + t_F	–	2TCL - 20 + t_F	ns
Address hold after $\overline{\text{RdCS}}$, $\overline{\text{WrCS}}$	t_{54}	CC	30 + t_F	–	2TCL - 20 + t_F	–	ns
Data hold after $\overline{\text{WrCS}}$	t_{56}	CC	30 + t_F	–	2TCL - 20 + t_F	–	ns

1) These parameters refer to the latched chip select signals ($\overline{\text{CSxL}}$). The early chip select signals ($\overline{\text{CSxE}}$) are specified together with the address and signal $\overline{\text{BHE}}$ (see figures below).

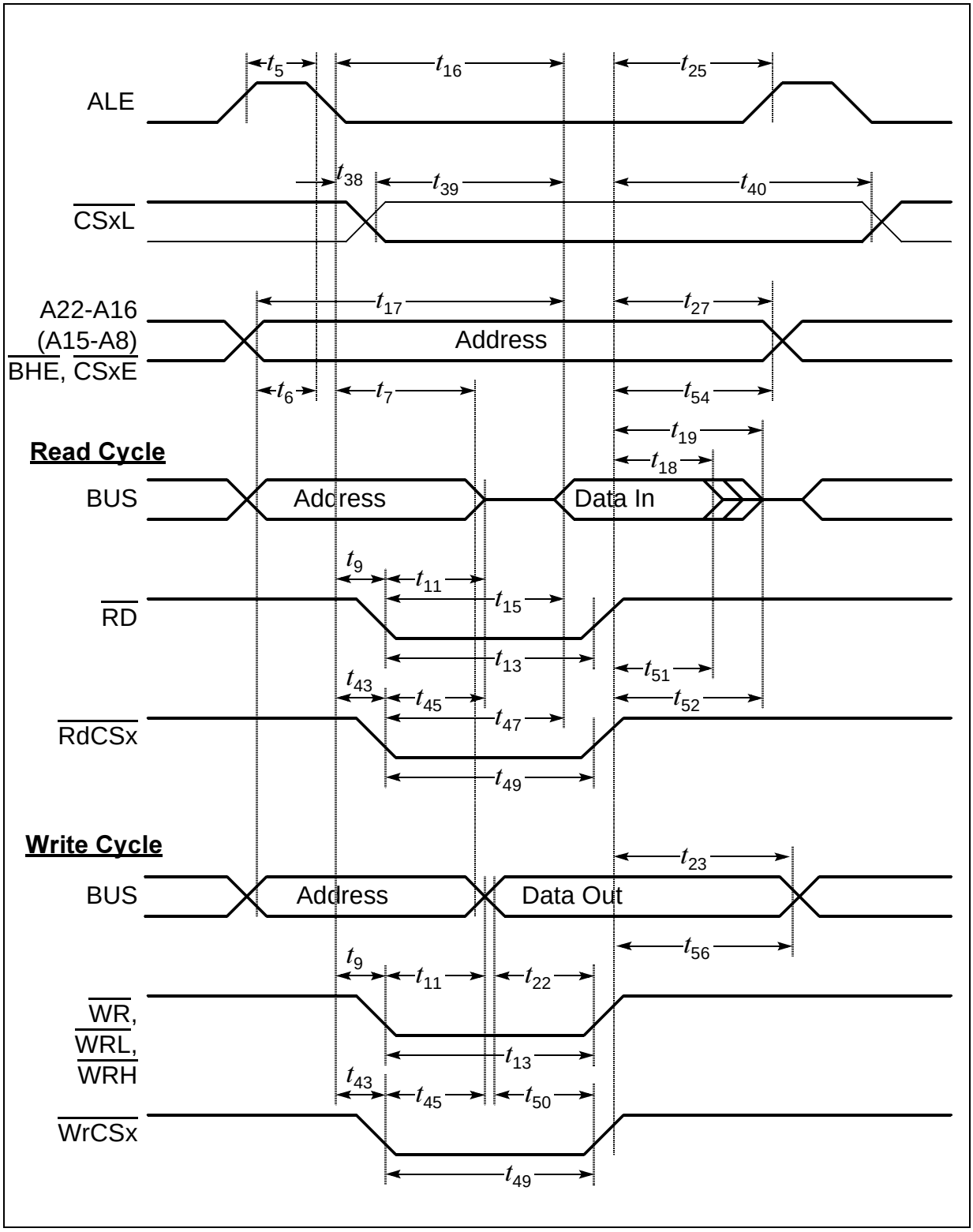


Figure 18 External Memory Cycle: Multiplexed Bus, No Read/Write Delay, Normal ALE

Demultiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
		min.	max.	min.	max.	
Address hold after RdCS, WrCS	t_{55} CC	-6 + t_F	–	-6 + t_F	–	ns
Data hold after WrCS	t_{57} CC	6 + t_F	–	TCL - 14 + t_F	–	ns

1) RW-delay and t_A refer to the next following bus cycle (including an access to an on-chip X-Peripheral).

2) Read data are latched with the same clock edge that triggers the address change and the rising RD edge. Therefore address changes before the end of RD have no impact on read cycles.

3) These parameters refer to the latched chip select signals (CSxL). The early chip select signals (CSxE) are specified together with the address and signal BHE (see figures below).

Demultiplexed Bus (Reduced Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol	Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
		min.	max.	min.	max.	
Address hold after RdCS, WrCS	t_{55} CC	-16 + t_F	–	-16 + t_F	–	ns
Data hold after WrCS	t_{57} CC	9 + t_F	–	TCL - 16 + t_F	–	ns

1) RW-delay and t_A refer to the next following bus cycle (including an access to an on-chip X-Peripheral).

2) Read data are latched with the same clock edge that triggers the address change and the rising RD edge. Therefore address changes before the end of RD have no impact on read cycles.

3) These parameters refer to the latched chip select signals (CSxL). The early chip select signals (CSxE) are specified together with the address and signal BHE (see figures below).

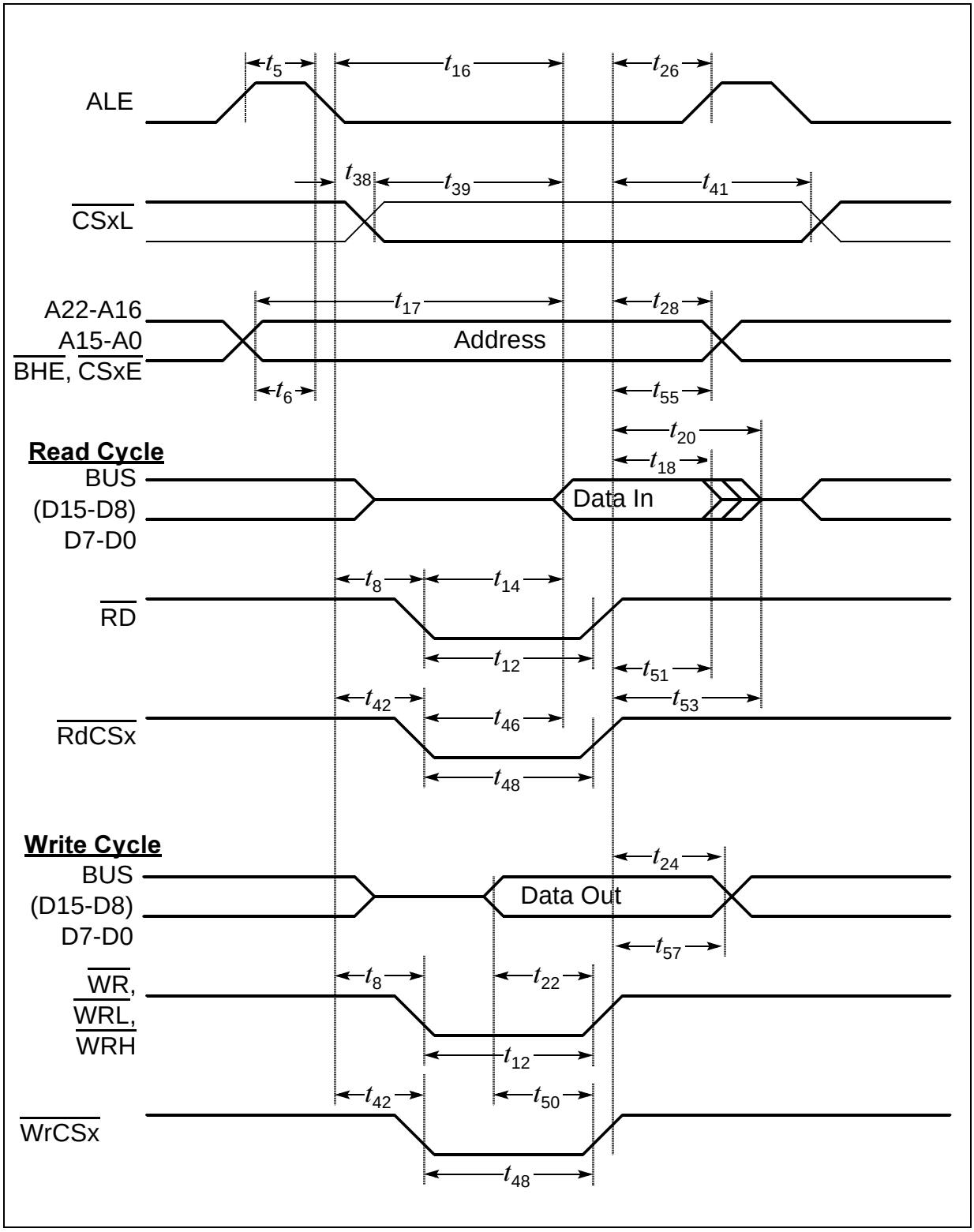


Figure 20 External Memory Cycle: Demultiplexed Bus, With Read/Write Delay, Normal ALE

AC Characteristics

CLKOUT and $\overline{\text{READY}}$ (Standard Supply Voltage Range)

(Operating Conditions apply)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
CLKOUT cycle time	t_{29}	CC	40	40	2TCL	2TCL	ns
CLKOUT high time	t_{30}	CC	14	–	TCL – 6	–	ns
CLKOUT low time	t_{31}	CC	10	–	TCL – 10	–	ns
CLKOUT rise time	t_{32}	CC	–	4	–	4	ns
CLKOUT fall time	t_{33}	CC	–	4	–	4	ns
CLKOUT rising edge to ALE falling edge	t_{34}	CC	0 + t_A	10 + t_A	0 + t_A	10 + t_A	ns
Synchronous $\overline{\text{READY}}$ setup time to CLKOUT	t_{35}	SR	14	–	14	–	ns
Synchronous $\overline{\text{READY}}$ hold time after CLKOUT	t_{36}	SR	4	–	4	–	ns
Asynchronous $\overline{\text{READY}}$ low time	t_{37}	SR	54	–	2TCL + t_{58}	–	ns
Asynchronous $\overline{\text{READY}}$ setup time [1]	t_{58}	SR	14	–	14	–	ns
Asynchronous $\overline{\text{READY}}$ hold time [1]	t_{59}	SR	4	–	4	–	ns
Async. $\overline{\text{READY}}$ hold time after $\overline{\text{RD}}$, $\overline{\text{WR}}$ high (Demultiplexed Bus) [2]	t_{60}	SR	0	0 + 2t_A + t_C + t_F [2]	0	TCL - 20 + 2t_A + t_C + t_F [2]	ns

1) These timings are given for test purposes only, in order to assure recognition at a specific clock edge.

2) Demultiplexed bus is the worst case. For multiplexed bus 2TCL are to be added to the maximum values. This adds even more time for deactivating $\overline{\text{READY}}$.
The 2t_A and t_C refer to the next following bus cycle, t_F refers to the current bus cycle.
The maximum limit for t_{60} must be fulfilled if the next following bus cycle is $\overline{\text{READY}}$ controlled.